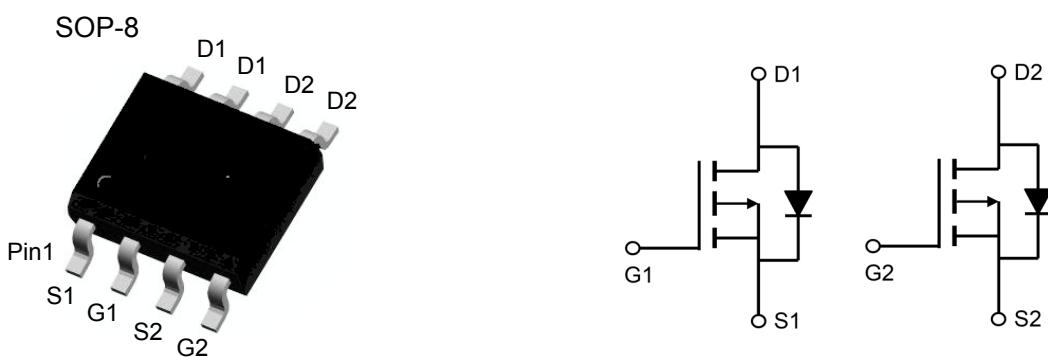


30V Dual P-Channel Enhancement-Mode MOSFET

General Description	Product Summary		
<ul style="list-style-type: none"> Low gate charge. Use as a load switch. Use in PWM applications 	<ul style="list-style-type: none"> BV_{DSS} -30V $R_{DS(on)}$ @$VGS = -10V$ < 55mΩ $R_{DS(on)}$ @$VGS = -4.5V$ < 60mΩ $R_{DS(on)}$ @$VGS = -2.5V$ < 80mΩ 		



Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)				
Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	V_{DS}	-30	V	
Gate-Source Voltage	V_{GS}	± 12	V	
Drain Current ($T_A=25^\circ C$)	I_D	-5.5	A	
Drain Current ($T_A=75^\circ C$)		-2.5	A	
Pulsed Drain Current ^a	I_{DM}	-20	A	
Power Dissipation ^b ($T_A=25^\circ C$)	P_D	2.0	W	
Power Dissipation ^b ($T_A=75^\circ C$)		1.4	W	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 ~ +150	°C	

Thermal Characteristics				
Parameter	Symbol	Maximum	Units	
Junction-to-Ambient ^a ($t \leq 10s$)	$R_{\theta JA}$	50	°C/W	
Junction-to-Ambient ^{a,d} (Steady-State)		90	°C/W	
Junction-to-Lead (Steady-State)	$R_{\theta JL}$	25	°C/W	

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)						
Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}$, $I_D = -250\mu\text{A}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = -30\text{V}$, $V_{\text{GS}} = 0\text{V}$			-1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}} = \pm 12\text{V}$, $V_{\text{DS}} = 0\text{V}$			± 100	nA
On Characteristics						
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = -250\mu\text{A}$	-1		-2.5	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}} = -10\text{V}$, $I_D = -5.5\text{A}$		48	55	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}$, $I_D = -4.5\text{A}$		55	60	$\text{m}\Omega$
		$V_{\text{GS}} = -2.5\text{V}$, $I_D = -2.5\text{A}$		70	80	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{\text{DS}} = -5\text{V}$, $I_D = -5.5\text{A}$		22		S
Drain-Source Diode Characteristics						
V_{SD}	Diode Forward Voltage	$V_{\text{GS}} = 0\text{V}$, $I_S = -1.0\text{A}$			-1.2	V
I_S	Maximum Body-Diode Continuous Current				-2.5	A
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}} = -15\text{V}$, $V_{\text{GS}} = 0\text{V}$ $f = 1.0\text{MHz}$		1020		pF
C_{oss}	Output Capacitance			125		pF
C_{rss}	Reverse Transfer Capacitance			85		pF
Switching Characteristics						
Q_g	Total Gate Charge	$V_{\text{DS}} = -15\text{V}$, $I_D = -5.5\text{A}$ $V_{\text{GS}} = -6\text{V}$		16		nC
Q_{gs}	Gate-Source Charge			4.8		nC
Q_{gd}	Gate-Drain Charge			4.5		nC
$t_{\text{D(ON)}}$	Turn-On Delay Time	$V_{\text{DD}} = -15\text{V}$, $I_D = -1\text{A}$ $V_{\text{GS}} = -6\text{V}$ $R_{\text{GEN}} = -6\text{ ohm}$		8.5		ns
t_r	Turn-On Rise Time			7.5		ns
$t_{\text{D(OFF)}}$	Turn-Off Delay Time			18		ns
t_f	Turn-Off Fall Time			5		ns

- a. Repetitive rating, Pulse width limited by junction temperature $T_{\text{J(MAX)}}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_{\text{J}}=25^\circ\text{C}$
- b. The power dissipation P_D is based on $T_{\text{J(MAX)}}=150^\circ\text{C}$, using $\leq 10\text{s}$ junction-to-ambient thermal resistance.
- c. The value of $R_{\theta_{\text{JA}}}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The value in any given application depends on the user's specific board design.
- d. The $R_{\theta_{\text{JA}}}$ is the sum of the thermal impedance from junction to lead $R_{\theta_{\text{JL}}}$ and lead to ambient.